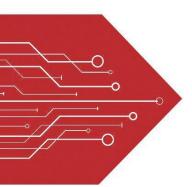
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data sheet



Semiconductor

Compiance

FEATURES

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications

- Low reverse leakage
 Built-in strain relief,ideal for automated placement
 High forward surge current capability
 High forward surge soldering guaranteed: 250°C/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body **Terminals**: Solder plated, solderable per MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end Mounting Position: Any

Weight: 0.002 ounce, 0.07 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

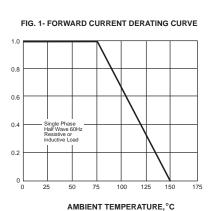
	SYMBOLS	M1	M2	М3	M4	M5	М6	M7	UNITS
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	VRMS	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V _{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at TL=75°C	l(AV)				1.0				Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	lfsm	30.0			Amps				
Maximum instantaneous forward voltage at 1.0A	V _F				1.1				Volts
Maximum DC reverse current Ta=25°C at rated DC blocking voltage Ta=100°C	lR	5.0 50.0		μА					
Typical junction capacitance (NOTE 1)	Cı				15.0				pF
Typical thermal resistance (NOTE 2)	Rθja	75.0		°C/W					
Operating junction and storage temperature range	ТЈ,Тѕтс	-65 to +150		°C					

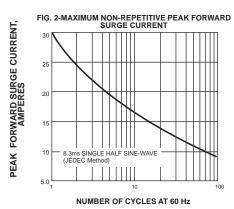
Note: 1. Measured at 1MHz and applied reverse voltage of 4.0V D.C. 2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

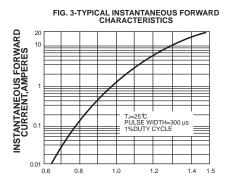


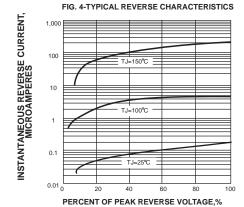




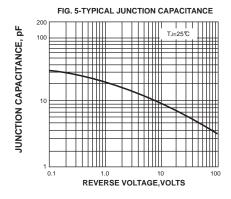


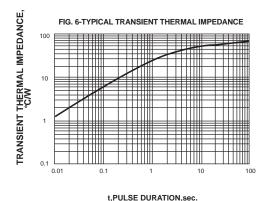






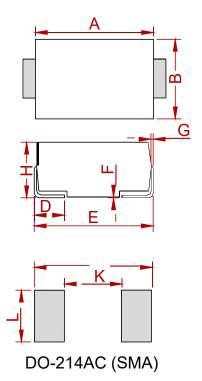








PACKAGE MECHANICAL DATA



	Dimensions					
Ref.	Millin	neters	Inches			
	Min.	Max.	Min.	Max.		
Α	4.25	4.65	0.167	0.183		
В	2.50	2.90	0.098	0.114		
С	1.35	1.65	0.053	0.065		
D	0.76	1.52	0.030	0.060		
Е	4.93	5.28	0.194	0.208		
F	0.051	0.203	0.002	0.008		
G	0.15	0.31	0.006	0.012		
Н	1.98	2.41	0.078	0.095		
J	6.50		0.256			
K		2.30		0.090		
L	1.70		0.067			

REEL SPECIFICATION

P/N	PKG	QTY
M1 THRU M7	SMA	2000



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